



Sierra Components, Inc.

2222 Park Place • Suite 3E • Minden, Nevada 89423

Phone: 775.783.4940 Fax: 775.783.4947

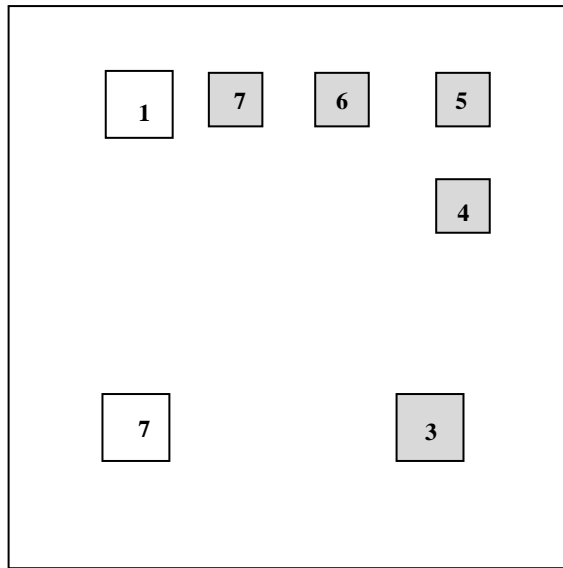
Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

PAD FUNCTION:

- 1 ANODE
- 2 CATHODE
- 3 N/C
- 4 N/C
- 5 N/C
- 6 N/C
- 7 N/C

.032"

.032"



Top Material: Al
 Backside Material: TiNiAg
 Bond Pad Size: .0035" x .0035" min.
 Backside Potential: GND
 Mask Ref:

APPROVED BY: DK

DIE SIZE .032" X .032"

DATE: 6/8/23

MFG: SILICON SUPPLIES

THICKNESS .011"

P/N: LM4040A-1.2